Form Type	Distribute	**Version**	2.0	**Ref**	IPC 1752A	**Sectionals**	Material Info	**Subsectionals**	D, A

Supplier Information

Company Name	TE Connectivity	**Request Document ID**		**Contact Name**	David Benfer	**Contact Title**	Product Compliance Engineer
Company Unique ID	TE Connectivity	**Response Date**	2015-05-20	**Contact Email**	dave.benfer@te.com		
Contact Phone Number		717-986-3725					

Legal Statement

Supplier Acceptance	true

Legal Statement

The information provided in this document is based upon reasonable inquiry of our suppliers. This information is subject to change. This information does not in any way modify existing purchase specifications or existing contractual or other agreements terms between TE Connectivity (or its affiliated companies) and its customers.

Product

Manufacturer Item number	2041021-4	**Amount**	1830.0	**Version**	-	**Identity**	
Manufacturer Item Name	Secure Digital Conn,top,Push-Pull,10 Au	**Weight Uom**	mg	**Mfr Site**		**Authority**	
Date		**UOM**	Each				

EURoHS-0508	Product(s) meets EU RoHS requirement without any exemptions
ChinaRoHS-0508	Product(s) is eligible for marking with the e code under China's Measures for Administration of the control of pollution by Electronic Information Products
EUREACH-1213	REACH Candidate Substances of Very High Concern ARE NOT Yet Reviewed

Product Disclosure

Sub-Item/Material/ Substance	**Level**	**Name**	**Substance Category**	**Substance CAS**	**Substance Concentration**	**Quantity**	**Mass per Unit**	**UOM**	**Exemption**
Material	1	Contacts plating_Sn				1.0	40.0	mg	
Substance	2	Tin	Supplier	7440-31-5	99.85	1.0	39.94	mg	
Substance	2	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-1212	0.15	1.0	0.06	mg	
Material	1	Shield cover plating_Au				1.0	20.0	mg	
Substance	2	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-1212	0.15	1.0	0.03	mg	
Substance	2	Gold	Supplier	7440-57-5	99.85	1.0	19.97	mg	
Material	1	Detect pin plating Sn				1.0	4.0	mg	
Substance	2	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-1212	0.15	1.0	0.0060	mg	
Substance	2	Tin	Supplier	7440-31-5	99.85	1.0	3.994	mg	
Material	1	Switch pin plating_Sn				1.0	4.0	mg	
Substance	2	Tin	Supplier	7440-31-5	99.85	1.0	3.994	mg	
Substance	2	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-1212	0.15	1.0	0.0060	mg	
Material	1	Switch pin plating_Ni				1.0	4.0	mg	
Substance	2	Nickel	Nickel	7440-02-0	99.76	1.0	3.9904	mg	
Substance	2	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-1212	0.24	1.0	0.0096	mg	
Material	1	Switch pin				1.0	54.0	mg	
Substance	2	Tin	Supplier	7440-31-5	8.0	1.0	4.32	mg	
Substance	2	Copper	Supplier	7440-50-8	91.9	1.0	49.626	mg	
Substance	2	Phosphorus	Supplier	7723-14-0	0.1	1.0	0.054	mg	
Material	1	Contacts plating_Au				1.0	20.0	mg	
Substance	2	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-1212	0.15	1.0	0.03	mg	
Substance	2	Gold	Supplier	7440-57-5	99.85	1.0	19.97	mg	

Material	1	Contacts plating_Ni				1.0	40.0	mg	
Substance	2	Nickel	Nickel	7440-02-0	99.76	1.0	39.904	mg	
Substance	2	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-1212	0.24	1.0	0.096	mg	
Material	1	Housing				1.0	504.0	mg	
Substance	2	1,4-Benzenedicarboxylic acid, polymer with [1,1-biphenyl]-4,4-diol, 4-hydroxybenzoic acid, 6-hydroxy-2-naphthalenecarboxylic acid and N-(4-hydroxyphenyl) acetamide	Supplier	147310-94-9	68.0	1.0	342.72	mg	
Substance	2	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-1212	2.0	1.0	10.08	mg	
Substance	2	Glass, oxide, chemicals	Supplier	65997-17-3	30.0	1.0	151.2	mg	
Material	1	Switch pin plating_Au				1.0	2.0	mg	
Substance	2	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-1212	0.15	1.0	0.0030	mg	
Substance	2	Gold	Supplier	7440-57-5	99.85	1.0	1.997	mg	
Material	1	Detect pin				1.0	57.0	mg	
Substance	2	Tin	Supplier	7440-31-5	8.0	1.0	4.56	mg	
Substance	2	Copper	Supplier	7440-50-8	91.9	1.0	52.383	mg	
Substance	2	Phosphorus	Supplier	7723-14-0	0.1	1.0	0.057	mg	
Material	1	Detect pin plating_ Ni				1.0	4.0	mg	
Substance	2	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-1212	0.24	1.0	0.0096	mg	
Substance	2	Nickel	Nickel	7440-02-0	99.76	1.0	3.9904	mg	
Material	1	Shield cover plating_Ni				1.0	20.0	mg	
Substance	2	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-1212	0.15	1.0	0.03	mg	
Substance	2	Nickel	Nickel	7440-02-0	99.85	1.0	19.97	mg	
Material	1	Contacts				1.0	55.0	mg	
Substance	2	Tin	Supplier	7440-31-5	8.0	1.0	4.4	mg	
Substance	2	Phosphorus	Supplier	7723-14-0	0.1	1.0	0.055	mg	
Substance	2	Copper	Supplier	7440-50-8	91.9	1.0	50.545	mg	
Material	1	Shield cover				1.0	1000.0	mg	
Substance	2	Nickel	Nickel	7440-02-0	9.8	1.0	98.0	mg	
Substance	2	Iron	Supplier	7439-89-6	69.0	1.0	690.0	mg	
Substance	2	Silicon	Supplier	7440-21-3	0.9	1.0	9.0	mg	
Substance	2	Manganese	Supplier	7439-96-5	1.7	1.0	17.0	mg	
Substance	2	Chromium	Supplier	7440-47-3	18.6	1.0	186.0	mg	
Material	1	Detect pin Au plating				1.0	2.0	mg	
Substance	2	Gold	Supplier	7440-57-5	99.85	1.0	1.997	mg	
Substance	2	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-1212	0.15	1.0	0.0030	mg	